* NOTICES *

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DETAILED DESCRIPTION

[Detailed Description of the Invention]
[0001]
[Industrial Application] This invention relates to the FPC substrate fixing approach to the conveyance plate which fixes a flexible printed circuit board (henceforth a FPC substrate) to a conveyance plate.
[0002]
[Description of the Prior Art] The 2nd approach of inserting a FPC substrate in the gage pin which makes the locating hole in the 1st approach of drawing an alignment line to a conveyance plate beforehand as an approach of making the FPC substrate from the former fixing to a conveyance plate, placing a FPC substrate according to the line, sticking adhesive tape on the front face, and carrying out positioning immobilization at a conveyance plate, and a FPC substrate, and was prepared in the conveyance plate, and carrying out positioning immobilization is learned. By the 1st conventional approach, alignment of the FPC substrate was carried out to the conveyance plate, it carried out temporary placing to it, and in order to stick adhesive tape on the front face of a conveyance plate, alignment had taken time amount. Moreover, the float by the deflection is generated that it is easy to deform since the FPC substrate is thin, and accurate alignment is not made. The adhesive tape removed when adhesive tape was moreover removed after attachment will curl, and will not be able to do a reuse, but will be thrown away. Furthermore, since the adhesion of adhesive tape was high, there were troubles, such as needing much time amount for removing a FPC substrate from a conveyance plate. It is necessary to make the locating hole made in the FPC substrate, and the gage pin prepared in the conveyance plate correspond by 1 to 1, therefore it needs to prepare the conveyance plate of dedication for every classification of a FPC substrate by the 2nd conventional approach. Moreover, when a deflection etc. is in a FPC substrate, a float is generated and accurate alignment is not made. When carrying out solder cream printing to a FPC substrate moreover, the gage pin of a conveyance plate became obstructive, and it had the trouble of being unable to perform adhesion printing.
[0003]
[Problem(s) to be Solved by the Invention] It was made in order to make an above-mentioned trouble solve this invention, can improve [the alignment of a FPC substrate] precision at few processes, and does not need the conveyance

plate of dedication for every classification, but can also make removal of a FPC substrate easy from a conveyance plate, and aims at moreover offering the FPC substrate fixing approach to the conveyance plate in which the reuse of adhesive tape is possible.

[0004]

[Means for Solving the Problem] The FPC substrate fixing approach to the conveyance plate by this invention The process which carries out two or more trains pasting of the high adhesiveness side of the double-sided tape which carried out the binder with which adhesiveness differs to both sides of a base material with ** in the approach of fixing a FPC substrate to a conveyance plate, and stuck the releasing paper at said conveyance plate, The process which equips a positioning guide plate with the conveyance plate with which the double-sided tape was stuck, It comes to have the process which equips a positioning guide plate with a substrate positioning fixture, and the process which is made to insert a FPC substrate in the tooling holes of a substrate positioning fixture, and is made to fix to the low adhesiveness side of a double-sided tape. The binder by the side of the low adhesiveness of a double-sided tape consists of a silicon system, and the binder by the side of high adhesiveness consists of acrylic.

[0005]

[Function] By sticking the double-sided tape which made the conveyance plate the binder with which adhesiveness differs with ** on two or more trains, a high adhesiveness side fixes certainly to a conveyance plate according to high adhesion. Since the location precision of a substrate can also position a FPC substrate well with a substrate positioning fixture and it fixes to the good detachability and low adhesiveness side of re-adhesiveness, while being able to make a FPC substrate exfoliate easily, without making it deformed and damaged, the reuse of a double-sided tape becomes possible. Since repeat use of a double-sided tape is attained while not preparing the conveyance plate of dedication for every classification of a FPC substrate, and not establishing the hole for positioning in a FPC substrate by this and being able to perform FPC substrate fixing to a conveyance plate and reduction and man day reduction of articles of consumption can be performed, a manufacturing cost can be reduced sharply.

[0006]

[Example] The example of the FPC substrate fixing approach to the conveyance plate by this invention is explained based on a drawing. Drawing 1 is the explanatory view showing the process of the FPC substrate fixing approach to the conveyance plate by this invention, and drawing 2 is the block diagram of the double-sided tape in the example of this invention. The array formation of the double-sided tape with which the adhesion material from which, as for a FPC substrate and 2, conveyance plates differ, and, as for 3, adhesiveness differs in to both sides in 1 in drawing 1 is carried out with **, and fixes to the conveyance plate 2, the positioning guide plate with which, as for 5, it be equipped with the conveyance plate 2, the substrate positioning fixture with which the positioning guide plate 5 be equipped with 6 with the conveyance plate 2 and the insertion hole of the number of predetermined in 7 be carried out, and they are the substrate tooling holes which position in a FPC substrate 1 and make fix to a

conveyance plate. In drawing 2 , four are a releasing paper by which laminating pasting is carried out on the front face of high adhesiveness side 3a and low adhesiveness side 3b the base material [with which 3 constitutes a double-sided tape and 8 constitutes a double-sided tape 3], high adhesiveness [to which, as for 3a, the binder of adhesion high on the front face of a base material 8 was carried out with **], and low adhesiveness side by which, as for 3b, detachability and the binder of re-adhesiveness were made with ** the front face of a base material 8.

[0007] The releasing paper of high adhesiveness side 3a of the double-sided tape 3 which consisted of the 1st process as shown in drawing 2 which made with ** the adhesion material from which adhesiveness differs both sides of a base material 8, and stuck the releasing paper 4 on them is removed, two or more trains pasting is beforehand carried out on the front face of the conveyance plate 2, and a double-sided tape is made to fix, respectively. Mizouchi for whom it was prepared by the positioning guide plate 5 is made to carry the conveyance plate 2 which the double-sided tape 3 fixed at the 2nd process. The positioning guide plate 5 is made to equip with the substrate positioning fixture 6 with which the substrate tooling holes 7 were formed in the conveyance plate 2 with which the positioning guide plate 5 was equipped in piles at the 3rd process. Remove the releasing paper by the side of the low adhesiveness of a double-sided tape 3, the substrate tooling holes 7 by which array formation was carried out are made to insert the FPC substrate 1 in the substrate positioning fixture 6, and the double-sided tape 3 of the conveyance plate 2 is made to fix at the 4th process. As a binder with which the adhesiveness made into both sides of the base material 12 which constitutes a double-sided tape 3 with ** in this example differs, the binder which consists of a silicon system with detachability and re-adhesiveness is used by the low adhesiveness side, and the binder which consists of acrylic with high adhesion is used by the high adhesiveness side.

[0008] Thus, a double-sided tape fixes certainly to a conveyance plate according to high adhesion by sticking the high adhesiveness side of the double-sided tape which carried out the binder with which adhesiveness differs with ** on a conveyance plate at two or more trains. Since it fixes to the low adhesiveness side of the double-sided tape which the FPC substrate was positioned by the substrate tooling holes 7, respectively, and fixed to the conveyance plate, a conveyance plate can be made to fix a FPC substrate with a sufficient location precision. Also when exfoliating the FPC substrate which exfoliation fixed to the binder in which re-adhesion is easy and possible from a conveyance plate, a FPC substrate by that of deformation and ** whose repeat use of a double-sided tape is attained while being able to exfoliate easily, without making it damaged It is not necessary to prepare the conveyance plate of dedication for every classification of a FPC substrate, and can be made to make it serve a double purpose with one kind of conveyance plate, and since articles of consumption, such as a man day for positioning and a double-sided tape, are reducible, a manufacturing cost can be made to mitigate sharply. In addition, if the binder used as a double-sided tape with ** is not limited to the binder of this example and has homogeneous ability, the same effectiveness is acquired and various combination is also possible for it.

[0009]
[Effect of the Invention] According to the FPC substrate fixing approach to the conveyance plate by this invention, a high adhesiveness side fixes certainly to a conveyance plate according to high adhesion by sticking the double-sided tape which made the conveyance plate the binder with which adhesiveness differs with ** on two or more trains. While being able to make it exfoliate easily, without deforming and damaging a FPC substrate, since the activity of printing of degree process etc. also becomes often [precision] and easy since a FPC substrate does not have a float with a sufficient location precision of the flat surface of a substrate, and the height direction by the substrate positioning fixture, either and it can position, and it fixes to a low adhesiveness side good [of detachability and re-adhesiveness], the reuse of a double-sided tape becomes possible. Thereby, it is not necessary to prepare the conveyance plate of dedication for every classification of a FPC substrate, and can be made to make it serve a double purpose by one kind. Moreover, since repeat use of a double-sided tape is attained while not establishing the hole for positioning in a FPC substrate and making FPC substrate fixing to a conveyance plate at it and reduction and man day reduction of articles of consumption can be performed, a manufacturing cost can be reduced sharply.

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CLAIMS

[Claim(s)]
[Claim 1] In the approach this invention fixes a FPC substrate (1) to a conveyance plate (2) The process which carries out two or more trains pasting of the high adhesiveness side of the double-sided tape (3) which made with ** the binder with which adhesiveness differs both sides of a base material (12), and stuck the releasing paper (4) on them at said conveyance plate, The process which equips a positioning guide plate (5) with the conveyance plate with which said double-sided tape was stuck, The FPC substrate fixing approach to the conveyance plate characterized by coming to have the process which equips said positioning guide plate with a substrate positioning fixture (6), and the process which is made to insert a FPC substrate (1) in the tooling holes (7) of said substrate positioning fixture, and is made to fix to the low adhesiveness side of said double-sided tape.
[Claim 2] It is the FPC substrate fixing approach to the conveyance plate according to claim 1 characterized by for the binder by the side of the low adhesiveness of said double-sided tape consisting of a silicon system, and the binder by the side of high adhesiveness consisting of acrylic.

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DESCRIPTION OF DRAWINGS

[Brief Description of the Drawings]
[Drawing 1] The explanatory view showing the process of the FPC substrate fixing approach to the conveyance plate by this invention.
[Drawing 2] The block diagram of the double-sided tape in the example of this invention.
[Description of Notations]
1 ... FPC Substrate
2 ... Conveyance Plate
3 ... Double-sided Tape
3a ... Quantity adhesiveness side
3b ... Low adhesiveness side
4 ... Releasing Paper
5 ... Positioning Guide Plate
6 ... Substrate Positioning Fixture
7 ... Substrate Tooling Holes
8 ... Base Material

[Translation done.]

PAT-NO: JP02000261193A

DOCUMENT-IDENTIFIER: JP 2000261193 A

TITLE: METHOD OF FIXING FPC BOARD TO CARRIER BOARD

PUBN-DATE: September 22, 2000

INVENTOR-INFORMATION:

NAME	COUNTRY
IWASA, KAZUHIRO	N/A

ASSIGNEE-INFORMATION:

NAME	COUNTRY
MISUZU KOGYO:KK	N/A

APPL-NO: JP11108367

APPL-DATE: March 11, 1999

INT-CL (IPC): H05K013/02

ABSTRACT:

PROBLEM TO BE SOLVED: To provide a method of fixing a flexible printed circuit(FPC) board to a carrier board whereby the FPC board can be exactly aligned and easily removed from the carrier board in a few processes, without an exclusive carrier board of every type, and adhesive tapes are reusable.

SOLUTION: The method comprises steps of pasting to a carrier board 2 a plurality of rows of higher-adhesive surfaces of double-sided tapes 3 each having coatings of adhesives different in adhesion on both surfaces of a base, mounting the carrier board 2 with the adhered tapes 3 on a positioning guide plate 5, mounting a board positioning **jig** 6 on the guide board 5, and inserting the FPC board 1 into a positioning hole 7 of the positioning **jig** 6 to rigidly fix it to the lower-adhesive surface of each tape 3. The adhesive of the lower- adhesive surface of the tape 3 is of a silicone material and that of the higher- adhesive surface is of an acrylic material.

DERWENT-ACC-NO: 2000-624933

DERWENT-WEEK: 200060

TITLE: Flexible printed circuit substrate fixing procedure, involves inserting substrate in locating hole of **jig** and fixing to low adhesive side of double sided tape

PATENT-ASSIGNEE: MISUZU IND CORP[MISUN]

PRIORITY-DATA: 1999JP-0108367 (March 11, 1999)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
JP 2000261193 A	September 22, 2000	N/A	003	H05K 013/02

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO	APPL-DATE
JP2000261193A	N/A	1999JP-0108367	March 11, 1999

INT-CL (IPC): H05K013/02

ABSTRACTED-PUB-NO: JP2000261193A

BASIC-ABSTRACT:

NOVELTY - Double sided tapes (3) are coated in multiple rows on the conveying board (2). The conveying board with tape is then installed in a locating guide plate (5). A substrate positioning **jig** (6) is then installed to the guide plate. A flexible printed circuit (FPC) substrate (1) is made to insert in location hole (7) of **jig** and is made to fix to silicon group adhesive side of double sided tape.

DETAILED DESCRIPTION - The double sided tape (3) has acrylic group adhesive side and silicon group adhesive side stuck to both sides of base material along with separate paper. The flexible printed circuit substrate is then made to

fix to the silicon group adhesive side of the tape.

USE - For fixing flexible printed circuit (FPC) substrate to conveying board.

ADVANTAGE - Performs reusage of adhesive tape thus reducing manufacturing cost greatly.

DESCRIPTION OF DRAWING(S) - The figure shows explanatory drawing of FPC substrate fixing procedure.

FPC Substrate 1

Conveying board 2

Double sided tape 3

Locating guide plate 5

Substrate positioning jig 6

Location hole 7

CHOSEN-DRAWING: Dwg.1/2

TITLE-TERMS: FLEXIBLE PRINT CIRCUIT SUBSTRATE FIX PROCEDURE

INSERT SUBSTRATE

LOCATE HOLE **JIG** FIX LOW ADHESIVE SIDE DOUBLE SIDE TAPE

DERWENT-CLASS: V04

EPI-CODES: V04-R04G; V04-R09; V04-R17;

SECONDARY-ACC-NO:

Non-CPI Secondary Accession Numbers: N2000-463738

(19)日本国特許庁（ＪＰ）　(12)公開特許公報（Ａ）　(11)特許出願公開番号
特開2000－261193
(P2000－261193A)
(43)公開日　平成12年９月22日(2000.9.22)

(51)Int.Cl.⁷	識別記号	ＦＩ	ﾃｰﾏｺｰﾄﾞ(参考)
Ｈ０５Ｋ　13/02		Ｈ０５Ｋ　13/02	Ｖ　５Ｅ３１３

審査請求　未請求　請求項の数２　書面　（全　３　頁）

(21)出願番号　特願平11－108367

(22)出願日　平成11年３月11日(1999.3.11)

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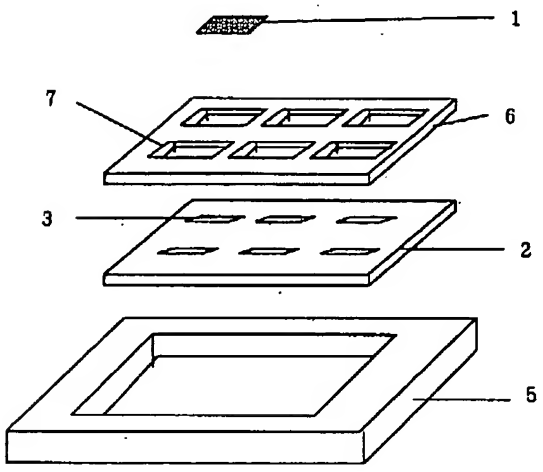
Ｆターム(参考)　5E313 AA12 CC05 DD13

(54)【発明の名称】　搬送板へのＦＰＣ基板固着方法

(57)【要約】
【目的】少ない工程でＦＰＣ基板の位置合わせが精度良くでき、種別ごとに専用の搬送板を必要とせず、搬送板からＦＰＣ基板の取り外しも容易にでき、しかも粘着テープの再使用が可能な搬送板へのＦＰＣ基板固着方法を提供する。
【構成】基材の両面に粘着性の異なる粘着剤を塗付し剥離紙を貼付した両面テープの高粘着性側を搬送板に複数列貼付する工程と、両面テープが貼付された搬送板を位置決め案内板に装着する工程と、位置決め案内板に基板位置決め治具を装着する工程と、基板位置決め治具の位置決め孔にＦＰＣ基板を挿入させ両面テープの低粘着性側に固着させる工程とを有してなり、両面テープの低粘着性側の粘着剤はシリコン系よりなり、高粘着性側の粘着剤はアクリル系よりなる。



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【特許請求の範囲】

【請求項1】本発明は、ＦＰＣ基板（１）を搬送板（２）に固定する方法において、基材（１２）の両面に粘着性の異なる粘着剤を塗付し剥離紙（４）を貼付した両面テープ（３）の高粘着性側を前記搬送板に複数列貼付する工程と、前記両面テープが貼付された搬送板を位置決め案内板（５）に装着する工程と、前記位置決め案内板に基板位置決め治具（６）を装着する工程と、前記基板位置決め治具の位置決め孔（７）にＦＰＣ基板（１）を挿入させ前記両面テープの低粘着性側に固着させる工程とを有してなることを特徴とする搬送板へのＦＰＣ基板固着方法。

【請求項2】前記両面テープの低粘着性側の粘着剤はシリコン系よりなり、高粘着性側の粘着剤はアクリル系よりなることを特徴とする請求項1記載の搬送板へのＦＰＣ基板固着方法。

【発明の詳細な説明】

【０００１】

【産業上の利用分野】本発明は、フレキシブルプリント基板（以下ＦＰＣ基板という）を搬送板に固定する搬送板へのＦＰＣ基板固着方法に関する。

【０００２】

【従来の技術】従来から、ＦＰＣ基板を搬送板に固定させる方法として、予め搬送板に位置合わせ線を引き、その線に合わせてＦＰＣ基板を置き、その表面に粘着テープを貼り付けて搬送板に位置決め固定する第１の方法と、ＦＰＣ基板に位置決め穴をあけておき、搬送板に設けた位置決めピンにＦＰＣ基板を嵌め込んで位置決め固定する第２の方法とが知られている。従来の第１の方法では、ＦＰＣ基板を搬送板に位置合わせして仮置きし、搬送板の表面に粘着テープを貼り付けるために位置合わせに時間がかかっていた。また、ＦＰＣ基板が薄いために変形し易くたわみによる浮きが発生し精度良い位置合わせができない。その上、貼り付け後に粘着テープを剥がすと剥がした粘着テープはカールしてしまい再使用ができず使い捨てになってしまう。さらに、粘着テープの粘着力が高いためにＦＰＣ基板を搬送板より取り外すのに多くの時間を必要とするなどの問題点があった。従来の第２の方法では、ＦＰＣ基板にあけた位置決め穴と搬送板に設けた位置決めピンとは１対１で対応させておく必要があり、そのためにＦＰＣ基板の種別ごとに専用の搬送板を用意しておく必要がある。また、ＦＰＣ基板にたわみなどがある時には浮きが発生し精度良い位置合わせができない。その上、ＦＰＣ基板への半田クリーム印刷をする時には搬送板の位置決めピンがじゃまになり、密着印刷ができないなどの問題点を有していた。

【０００３】

【発明が解決しようとする課題】本発明は、上述の問題点を解決させるためになされたもので、少ない工程でＦＰＣ基板の位置合わせが精度良くでき、種別ごとに専用の搬送板を必要とせず、搬送板からＦＰＣ基板の取り外しも容易にでき、しかも粘着テープの再使用が可能な搬送板へのＦＰＣ基板固着方法を提供することを目的とするものである。

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【０００４】

【課題を解決するための手段】本発明による搬送板へのＦＰＣ基板固着方法は、ＦＰＣ基板を搬送板に固定する方法において、基材の両面に粘着性の異なる粘着剤を塗付し剥離紙を貼付した両面テープの高粘着性側を前記搬送板に複数列貼付する工程と、両面テープが貼付された搬送板を位置決め案内板に装着する工程と、位置決め案内板に基板位置決め治具を装着する工程と、基板位置決め治具の位置決め孔にＦＰＣ基板を挿入させ両面テープの低粘着性側に固着させる工程とを有してなり、両面テープの低粘着性側の粘着剤はシリコン系よりなり、高粘着性側の粘着剤はアクリル系よりなる。

【０００５】

【作用】搬送板に粘着性の異なる粘着剤を塗付した両面テープを複数列に貼付することにより、高粘着性側は高い粘着力により搬送板に確実に固着される。ＦＰＣ基板は基板位置決め治具により基板の位置精度も良く位置決めでき、剥離性と再粘着性の良い低粘着性側に固着されるので、ＦＰＣ基板を変形、損傷させることなく容易に剥離させることができると共に両面テープの再使用が可能となる。これにより、ＦＰＣ基板の種別ごとに専用の搬送板を用意する必要もなく、また、ＦＰＣ基板に位置決め用の穴を設ける必要もなく、搬送板へのＦＰＣ基板固着ができると共に両面テープの繰り返し使用が可能となることから消耗品の節減と工数削減ができるので、製造コストを大幅に低減させることができる。

【０００６】

【実施例】本発明による搬送板へのＦＰＣ基板固着方法の実施例を図面に基づいて説明する。図１は、本発明による搬送板へのＦＰＣ基板固着方法の工程を示す説明図であり、図２は、本発明の実施例における両面テープの構成図である。図１において、１はＦＰＣ基板、２は搬送板、３は両面に粘着性の異なる粘着材が塗付され搬送板２に固着される両面テープ、５は搬送板２が装着される位置決め案内板、６は搬送板２と共に位置決め案内板５に装着される基板位置決め治具、７は所定の数の挿入穴が配列形成されＦＰＣ基板１を位置決めし搬送板に固定させる基板位置決め孔である。図２において、３は両面テープ、８は両面テープ３を構成する基材、３ａは基材８の表面に高い粘着力の粘着剤が塗付された高粘着性側、３ｂは基材８の表面に剥離性、再粘着性の粘着剤が塗付された低粘着性側、４は高粘着性側３ａと低粘着性側３ｂの表面に積層貼付される剥離紙である。

【０００７】第１の工程では、基材８の両面に粘着性の異なる粘着材を塗付し剥離紙４を貼付した図２に示すように構成された両面テープ３の高粘着性側３ａの剥離紙

を剥がし、予め搬送板２の表面に複数列貼付して両面テープをそれぞれ固着させる。第２の工程では、両面テープ３が固着された搬送板２を位置決め案内板５に設けられた溝内に装着させる。第３の工程では、位置決め案内板５に装着された搬送板２に重ねて基板位置決め孔７が設けられた基板位置決め治具６を位置決め案内板５に装着させる。第４の工程では、両面テープ３の低粘着性側の剥離紙を剥がし、基板位置決め治具６に配列形成された基板位置決め孔７にＦＰＣ基板１を挿入させ搬送板２の両面テープ３に固着させる。本実施例において、両面テープ３を構成する基材１２の両面に塗付される粘着性の異なる粘着剤として、低粘着性側は剥離性、再粘着性があるシリコン系よりなる粘着剤が使用され、高粘着性側は高い粘着力があるアクリル系よりなる粘着剤が使用されている。

【０００８】このようにして、粘着性の異なる粘着剤を塗付した両面テープの高粘着性側を搬送板に複数列に貼付することにより、両面テープは高い粘着力により搬送板に確実に固着される。ＦＰＣ基板はそれぞれ基板位置決め孔７に位置決めされて搬送板に固着された両面テープの低粘着性側に固着されるので、ＦＰＣ基板を位置精度良く搬送板に固着させることができる。剥離が容易で再粘着可能な粘着剤に固着されたＦＰＣ基板を搬送板より剥離するときも、ＦＰＣ基板を変形、損傷させることなく容易に剥離することができると共に両面テープの繰り返し使用が可能となるるので、ＦＰＣ基板の種別ごとに専用の搬送板を用意する必要もなく１種類の搬送板で兼用させることができ、位置決めのための工数や両面テープなどの消耗品を節減できることから製造コストを大幅に軽減させることができる。なお、両面テープに塗付される粘着剤は、本実施例の粘着剤に限定されるものではなく同性能を有するものであれば同様な効果が得られ、種々の組み合わせも可能である。

【０００９】

【発明の効果】本発明による搬送板へのＦＰＣ基板固着方法によれば、搬送板に粘着性の異なる粘着剤を塗付した両面テープを複数列に貼付することにより、高粘着性側は高い粘着力により搬送板に確実に固着される。ＦＰＣ基板は基板位置決め治具により基板の平面と高さ方向の位置精度も良く浮きもなく位置決めできるので、次工程の印刷などの作業も精度良く容易になり、剥離性と再粘着性の良い低粘着性側に固着されるので、ＦＰＣ基板を変形、損傷させることなく容易に剥離させることができると共に両面テープの再使用が可能となる。これにより、ＦＰＣ基板の種別ごとに専用の搬送板を用意する必要もなく１種類で兼用させることができる。また、ＦＰＣ基板に位置決め用の穴を設ける必要もなく、搬送板へのＦＰＣ基板固着ができると共に両面テープの繰り返し使用が可能となることから消耗品の節減と工数削減ができるので、製造コストを大幅に低減させることができる。

【図面の簡単な説明】

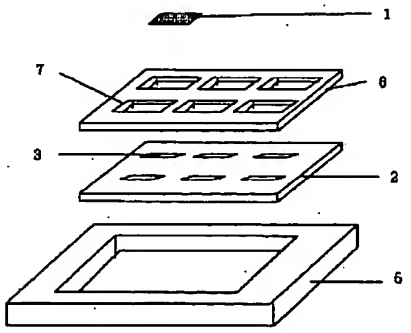
【図１】本発明による搬送板へのＦＰＣ基板固着方法の工程を示す説明図。

【図２】本発明の実施例における両面テープの構成図。

【符号の説明】

１　・・・　ＦＰＣ基板
２　・・・　搬送板
３　・・・　両面テープ
３ａ・・・　高粘着性側
３ｂ・・・　低粘着性側
４　・・・　剥離紙
５　・・・　位置決め案内板
６　・・・　基板位置決め治具
７　・・・　基板位置決め孔
８　・・・　基材

【図１】



【図２】